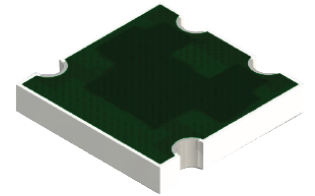


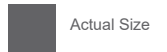
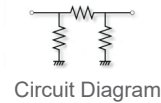
ATC2525CT-1000JN-99 Features:

- PI Configuration
- RoHS Compliant
- Solderable Terminals
- Customer Defined Testing Available
- Symmetrical Design¹
- Tape & Reel or Waffle Pack Available (Standard is bulk)



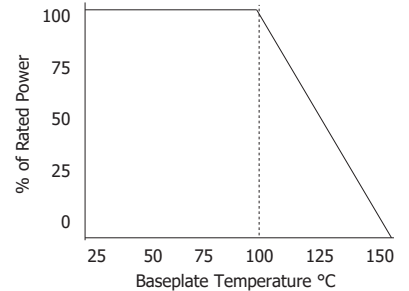
ATC2525CT-1000JN-99 Parameters:

Nominal Attenuation:	10dB
Operating Frequency:	DC - 2GHz*
Attenuation Accuracy:	9.7dB min., 10.7 max.
Rated Power:	27W**
Return Loss:	16dB min.
Impedance:	50Ω
DC Resistance In to Out:	51.95Ω (part ID only)
Construction:	Thick Film on BeO
Operating Temperature:	-55 to +150°C
Baseplate to resistor film thermal resistance:	5.4°C/Watt with 250°C max. film temperature

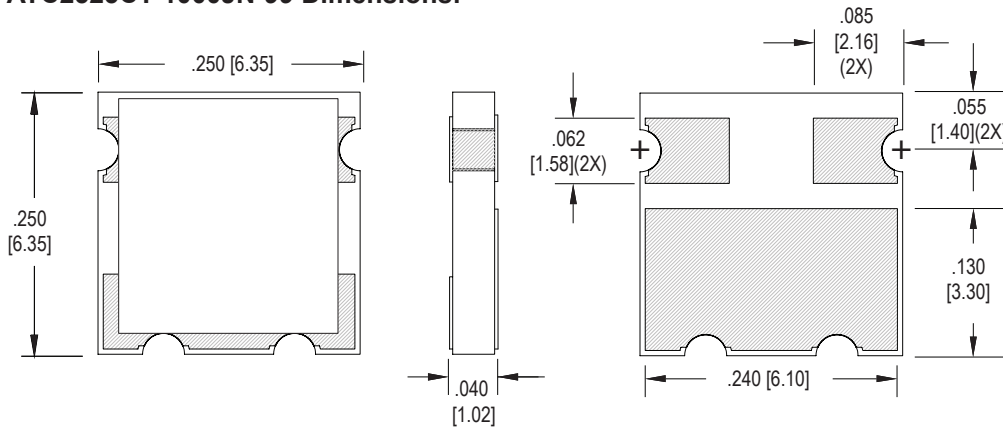


¹ Can be mounted in either direction
 * In a matched, continuous 50Ω system with proper workmanship
 ** Rating based on ≤100°C constant baseplate temperature, for other situations use thermal resistance

ATC2525CT-1000JN-99 Power Derating Curve



ATC2525CT-1000JN-99 Dimensions:



Dimensions in inches [mm]
 Tolerance is ± 0.005 [0.13]
 unless otherwise stated

Ordering Information:

ATC	2525	CT	-	1000	JN	-	99	UU
Prefix for 3 Sided Wraparound Attenuator w/ Castellations				Value Code 1000 - 10dB	Normal Inspection Contact factory for additional options		Substrate 99 - 0.040" BeO	Packaging Blank - Bulk TR - Tape and Reel WP - Waffle Pack
Size 2525								
Terminal Metallization	RoHS	Magnetic	Solder	Epoxy	Wirebond			
CT - 100% Matte Tin over Nickel over Silver	Yes	Yes	Yes	No	No			

Barry Industries reserves the right to change part number and/or process without notification.

ATC2525CT-1000JN-99 Reliability Specifications:

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65°C to +150°C 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

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